N-Channel Enhancement Mode Power MOSFET

Description

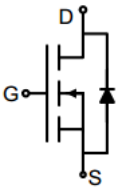
The G2012 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge. It can be used in a wide variety of applications.

General Features

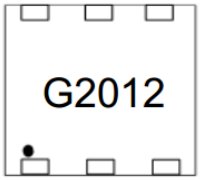
- V_{DS} 20V
- I_D (at V_{GS} = 10V) 12A
- $R_{DS(ON)}$ (at V_{GS} = 4.5V) < 12mΩ
- $R_{DS(ON)}$ (at V_{GS} = 2.5V) < 18mΩ
- 100% Avalanche Tested
- RoHS Compliant

Application

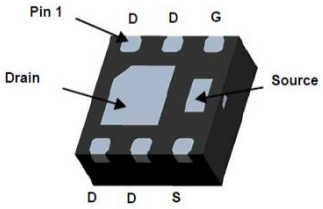
- Power switch
- DC/DC converters



Schematic diagram



Marking and pin assignment



DFN2*2-6L

Device	Package	Marking	Packaging
G2012	DFN2*2-6L	G2012	3000pcs/Reel

Absolute Maximum Ratings T_C = 25ºC, unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	20	V
Continuous Drain Current	I_D	12	A
Pulsed Drain Current (note1)	I_{DM}	40	A
Gate-Source Voltage	V_{GSS}	±10	V
Power Dissipation	P_D	1.5	W
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 To 150	ºC

Thermal Resistance

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Ambient	R_{thJA}	83	ºC/W

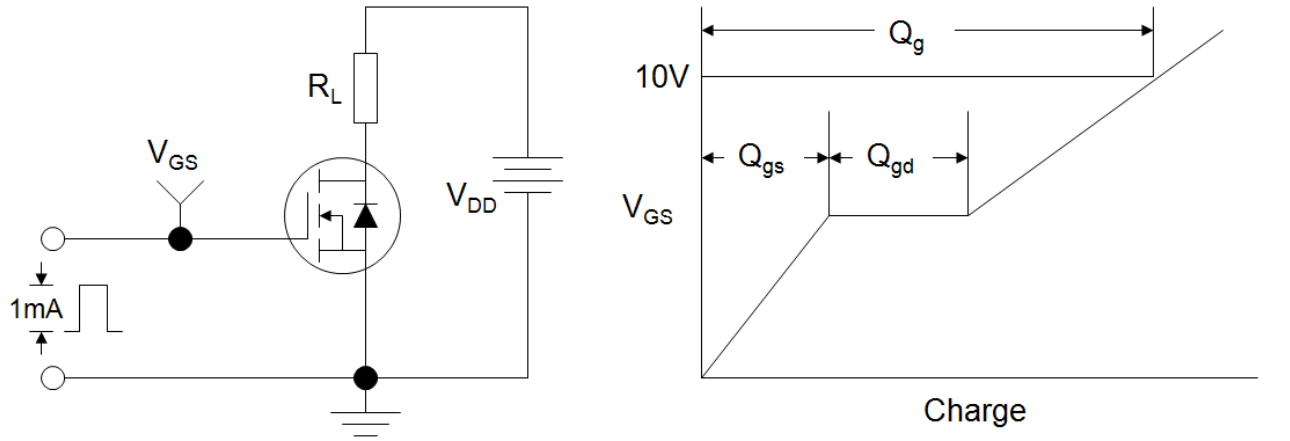
Specifications T_J = 25ºC, unless otherwise noted

Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
Static Parameters						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS} = 0V, I_D = 250μA	20	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 20V, V_{GS} = 0V, T_J = 25ºC	--	--	1	μA
Gate-Source Leakage	I_{GSS}	V_{GS} = ±10V	--	--	±100	nA
Gate-Source Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250μA	0.35	0.7	1	V
Drain-Source On-Resistance	$R_{DS(on)}$	V_{GS} = 4.5V, I_D = 5A	--	7.3	12	mΩ
		V_{GS} = 2.5V, I_D = 5A	--	8.8	18	
Forward Transconductance	g_{FS}	VDS=10V,ID=5A	--	5	--	S
Dynamic Parameters						
Input Capacitance	C_{iss}	V_{GS} = 0V, V_{DS} = 10V, f = 1.0MHz	--	1255	--	pF
Output Capacitance	C_{oss}		--	220	--	
Reverse Transfer Capacitance	C_{rss}		--	180	--	
Total Gate Charge	Q_g	V_{DD} = 10V, I_D = 10A, V_{GS} = 10V	--	29	--	nC
Gate-Source Charge	Q_{gs}		--	5.2	--	
Gate-Drain Charge	Q_{gd}		--	6.3	--	
Turn-on Delay Time	$t_{d(on)}$	V_{DD} = 10V, I_D = 5A, R_G = 50Ω	--	300	--	ns
Turn-on Rise Time	t_r		--	1000	--	
Turn-off Delay Time	$t_{d(off)}$		--	4000	--	
Turn-off Fall Time	t_f		--	2500	--	
Drain-Source Body Diode Characteristics						
Continuous Body Diode Current	I_S	T_C = 25ºC	--	--	12	A
Body Diode Voltage	V_{SD}	T_J = 25ºC, I_{SD} = 10A, V_{GS} = 0V	--	--	1.2	V

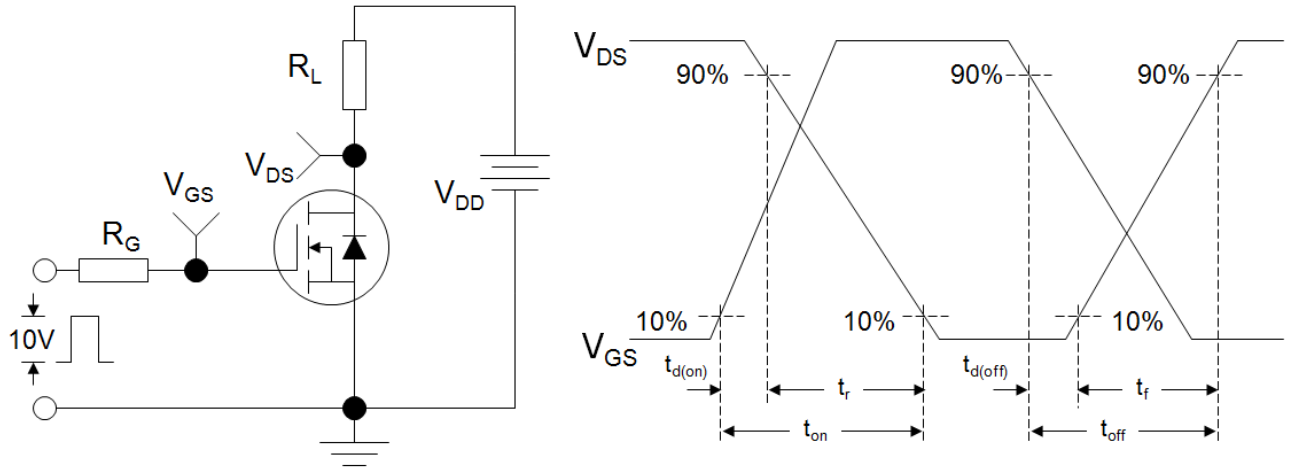
Notes

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. Identical low side and high side switch with identical R_G

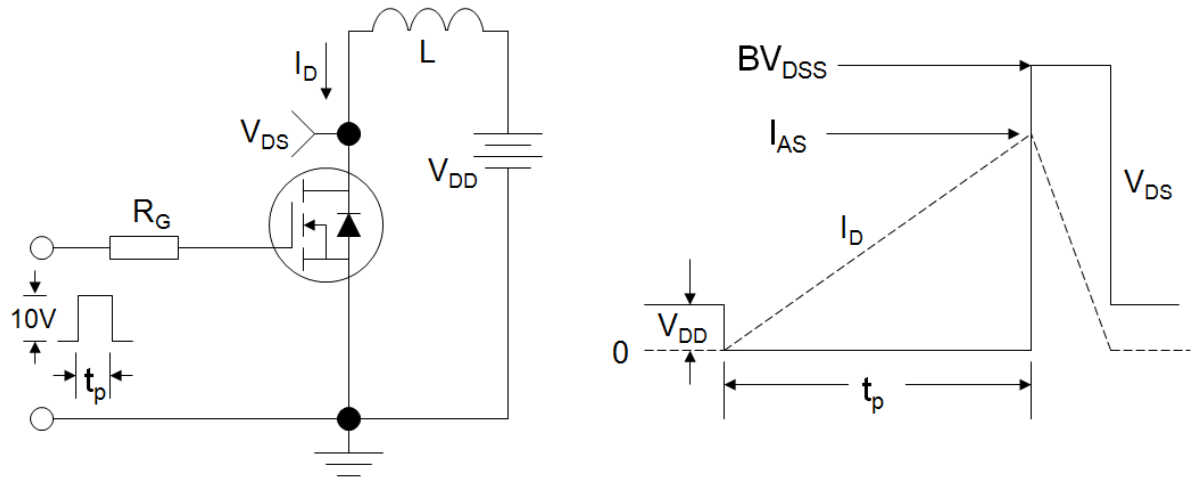
Gate Charge Test Circuit



EAS Test Circuit



Switch Time Test Circuit



Typical Characteristics T_J = 25ºC, unless otherwise noted

Figure 1. Output Characteristics

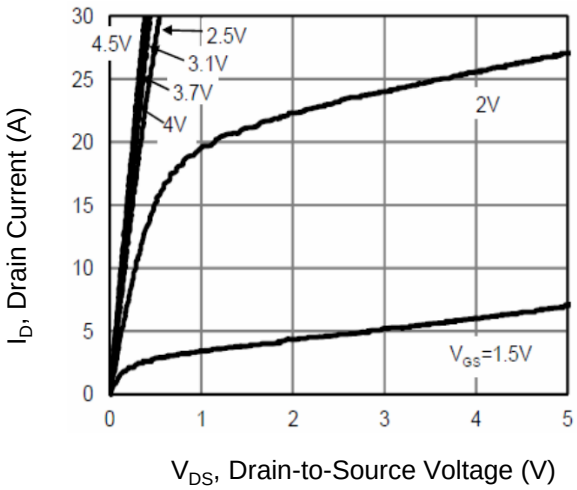


Figure 2. Transfer Characteristics

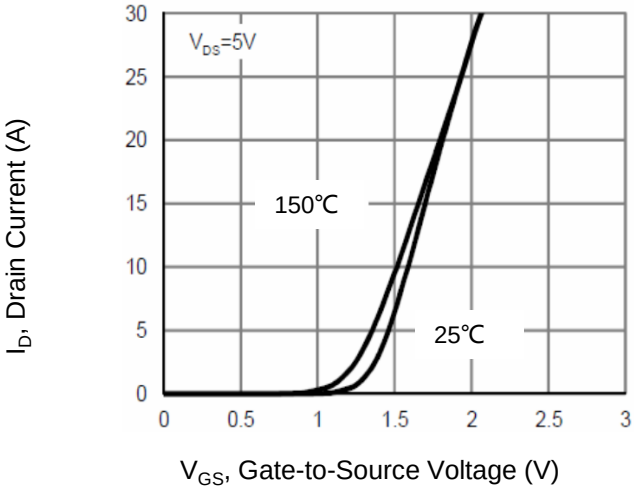


Figure 3.Rdson-Drain Current

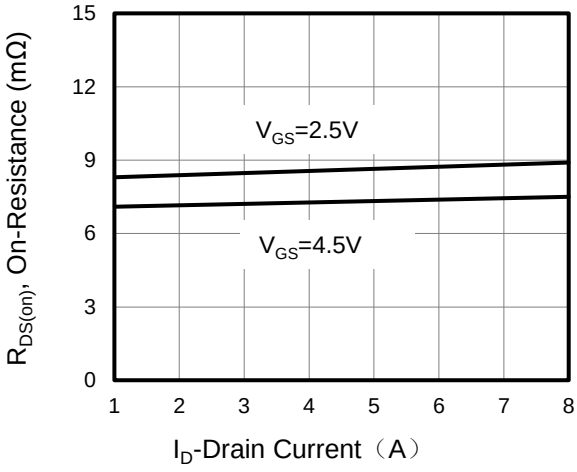


Figure 4. Gate Charge

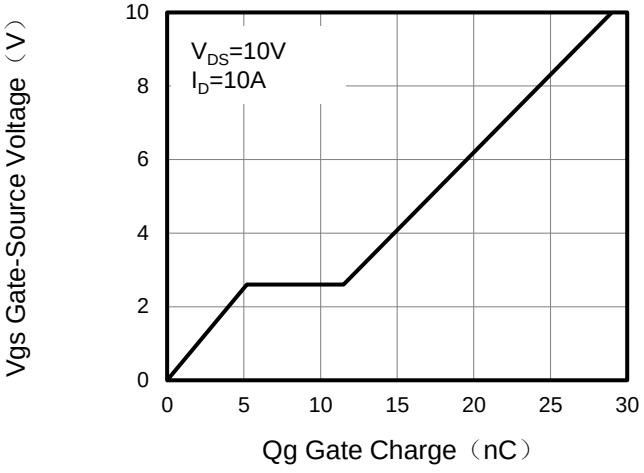


Figure 5. Capacitance vs Vds

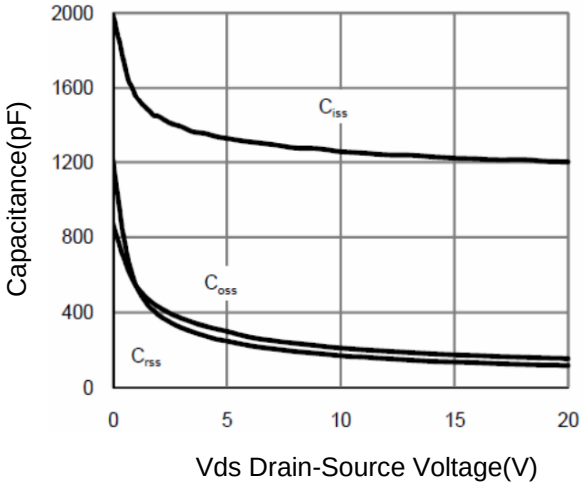
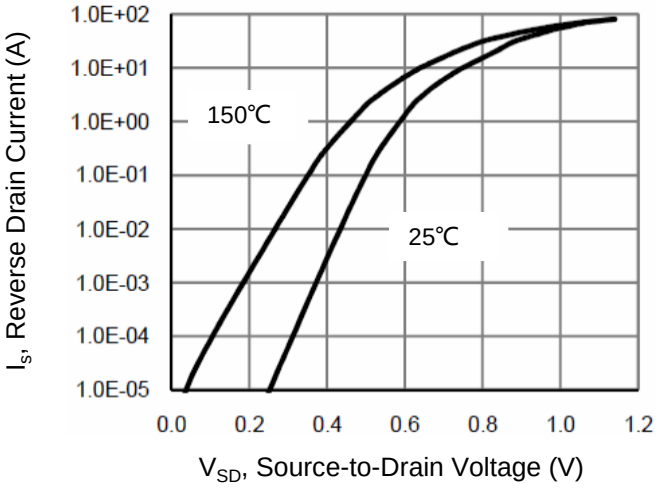


Figure 6. Source-Drain Diode Forward



Typical Characteristics T_J = 25ºC, unless otherwise noted

Figure 7. Drain-Source On-Resistance

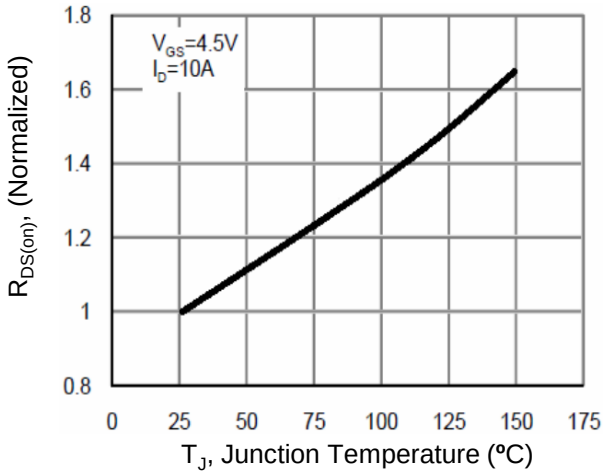


Figure 8. Safe Operation Area

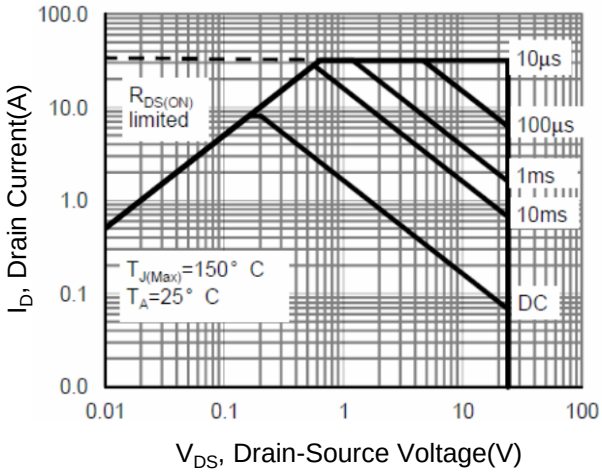
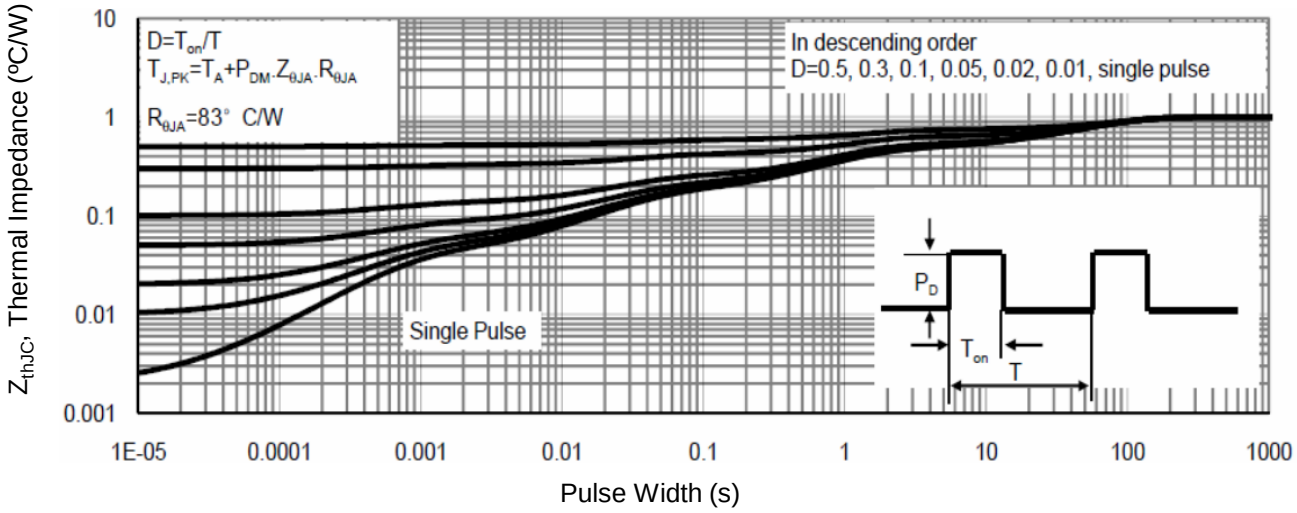
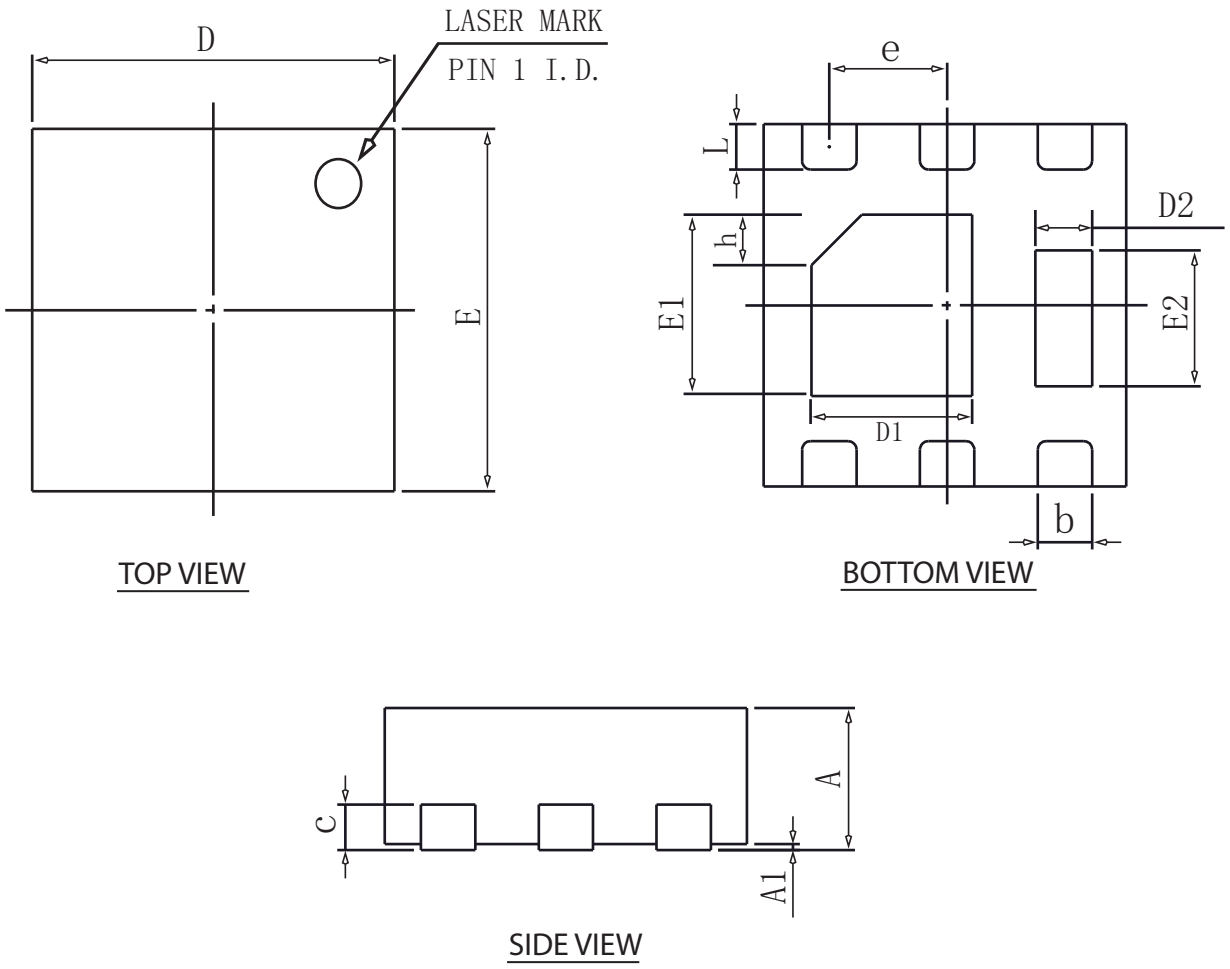


Figure 9. Normalized Maximum Transient Thermal Impedance



DFN2×2-6L Package Information



COMMON DIMENSIONS

SYMBOL	mm		
	MIN	NOM	MAX
A	0.70	0.75	0.80
A1	NA	0.02	0.05
b	0.20	0.27	0.34
c	0.18	0.20	0.25
D	1.95	2.00	2.07
E	1.95	2.00	2.07
D1	0.80	0.90	1.00
E1	0.90	1.00	1.10
D2	0.20	0.30	0.40
E2	0.65	0.75	0.85
L	0.20	0.25	0.35
h	0.20	0.25	0.30
e	0.65BSC		